

X10846

Components and Spares



HEATSINK COMPOUND SYRINGE

TM 500 Thermal Grease Paste CPU



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KEY FEATURES:

- ✓ **Composition:** Made up of 5% silicone, 65% carbon, and 30% metal oxide compounds.
- ✓ **Thermal Properties:** Offers excellent thermal conductivity (>1.93 W/m-K) and low thermal impedance (<0.073 °C*in²/W).
- ✓ **Physical Characteristics:** It's grey, has a specific gravity of 2.5, and works effectively from -30°C to 300°C.
- ✓ **Stability:** Shows minimal evaporation (0.001%) and bleed (0.05%) over 24 hours at 150°C, ensuring long-term reliability.
- ✓ **Electrical Insulation:** Provides good electrical insulation with a dielectric constant of 5.1 at 100Hz.

APPLICATIONS:

TM500 is essential for heat management in various tech devices:

- **PCs & Laptops:** Cooling CPUs/GPUs.
- **LEDs:** Managing heat.
- **Electronics:** Securing power components.
- **Machines:** Industrial heat control.

A heatsink compound syringe is a handy tool for applying thermal paste to electronic components that need efficient cooling. Thermal paste is a substance that fills the gaps between the heatsink and the component, improving heat transfer and preventing overheating. A syringe allows you to apply the right amount of paste with precision and ease. Here are some features and benefits of using a heatsink compound syringe:

- It contains high-quality thermal paste that has high thermal conductivity, low metallic impurity content, and excellent moisture buffer.
- It has a needle tip that lets you control the flow and direction of the paste, avoiding spills and waste.
- It is compatible with most types of heatsinks and electronic components.
- It is easy to use and store, requiring no special tools or skills.

TECHNICAL SPECIFICATIONS

Items	Units	Environment	Test method	Test result
Colour	No	25°C	Visual	Grey
Thermal Conductivity	W/m-K	No	ROCT8.140-82	>1.93
Thermal Impedance	°C-in ² /W	No	ROCT8.140-82	<0.073
Specific Gravity	No	25°C	ASTM D1475	2.5
Evaporation	%	150°C/24Hours	Fed.Std.791	0.001
Bleed	%	150°C/24Hours	Fed.Std.791	0.05
Dielectric Constant	No	100Hz	ASTM D150	5.1
Viscosity	No	25°C	_____	NON
Thixotropic Index	1/10 mm	25°C	GB/T-269	380±10
Moment Beared Temperature	°C	No	No	-50~340°C
Operation Temperature	°C	No	No	-30~300°C

Compounds

Silicone Compounds	5%
Carbon Compounds	65%
Metal Oxide Compounds	30%

※ The product temperature, not spontaneous combustion, mining the general methods can be stored at room temperature

PRODUCT CODE AND RELATED PRODUCT CODE

Product Code	Product Description
Z01062	1g Heatsink compound syringe

YOU MUST READ THIS BEFORE INSTALLATION

ELECTRICAL SAFETY WARNING: RISK OF ELECTRIC SHOCK Always consult the Installation & Maintenance Instructions before connecting this product to the power supply. WARNING: Disconnect Power Before Servicing Ensure the electrical supply is safely disconnected before connecting to any supply, load, or control terminals.	INSTALLATION REQUIREMENTS WARNING: Installation by Qualified Personnel Only This product must only be installed or fitted by a competent, qualified installer familiar with the relevant electrical standards and installation practices.	USER RESTRICTIONS WARNING: Not for Use by Vulnerable Individuals This product is not intended for use by persons (including children) with reduced physical, sensory or mental capabilities, or lack of experience and knowledge, unless they are supervised or instructed by a person responsible for their safety.	USAGE ENVIRONMENT WARNING: Industrial Use Only This is an industrial-grade product and is not intended for household use.	HOT SURFACE WARNING WARNING: Hot Surfaces On certain models, surfaces marked with this symbol become hot during use. Avoid direct contact and follow all thermal safety precautions.
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